IN THE SPECIFICATION:

Please replace paragraph [0026] with the following amended paragraph. Applicant respectfully submits the amendments reflect corrections for minor typos to the detailed description and no new matter has been added.

[0026] **FIGS. 3A – 3B** illustrate an alternative embodiment of the progression of changing a visible surface of PCB 100 (as described above with respect to **FIG. 1**) from a first visible state to a second visible state. **FIG. 3A** illustrates a visible surface 140 disposed above PCB 100 having a first color 160. Visible surface 140 has a first color 160, and this first color may be from the color of thermochromatic material 120, the color of solder mask layer 115, or the color of any other layer of PCB 100 not covered by an opaque surface or material. In one embodiment, visible surface 140 may be the result of leucodye or NIPAM disposed over solder mask layer 115 to produce first color 160. As the temperature of PCB increases to a particular activation temperature of the leucodye or NIPAM, visible surface 140 becomes transparent to reveal a marking (represented by ~~"LOGO" 160~~ "LOGO" 162) printed on solder mask layer 115, as illustrated in **FIG. 3B**. Marking ~~160~~ 162 may be a product identifier for PCB 100 or other types of informational markings found on carrier substrates. The use of leucodyes and NIPAM allow for the visualization of thermal differentials on PCB 100 as well as other markings on solder mask layer ~~160~~ 115. For example, the label "HOT" may be printed on solder mask layer 115 to provide a visible warning when a temperature of PCB 100 has exceeded a certain level. Other labels or markings may also be placed on individual components coupled to PCB 100 including, but not limited to, memory chips, daughter cards, processors, etc.